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To members of the press

Japan Electronics and Information Technology Industries Association (JEITA)

**Contribution to Customer and Societal Development on the Semiconductor Industry Association in Japan and by Building a Framework for Disaster Preparedness**

Preparation of Compilation of Technical Case Studies Directed at Semiconductor Plants for Earthquake Countermeasures

Today the Semiconductor Industry Association in Japan (JSIA) (Chairperson, Semiconductor Board (JSIA) : Tetsuya Tsurumaru, Representative Director & Chairman, Renesas Electronics Corporation) of the Japan Electronics and Information Technology Industries Association (JEITA) announced that the JSIA has prepared the "Compilation of Technical Case Studies on Earthquake Countermeasures", which pools the technologies and know-how of all of the companies that are members of the Semiconductor Industry Association in Japan.

Because of the lessons of earthquakes such as the Great East Japan (Tohoku) Earthquake and Kumamoto earthquakes, the Semiconductor Industry Association in Japan formed the Business Continuity Management Task Force (BCM-TF) within the Semiconductor Industry Association in Japan in August of 2016, and this task force has continued a study on disaster preparedness and on building a framework for cooperation when a disaster occurs. The focus by BCM-TF has been on the area of coordination of seismic reinforcement technologies for semiconductor plants as disaster preparedness, and the task force has most recently prepared the Compilation of Technical Case Studies on Earthquake Countermeasures, which pools the technologies and know-how of each company. This compilation of case studies is made to be shared between companies that are members of BCM-TF and with firms each company does business with. It pulls together cases of the hardware and management of production plants, and includes items such as past cases of the damage from and countermeasures for earthquakes, seismic reinforcement measures for plant and equipment, and techniques for information sharing. The plan is that reinforcement (retrofitting) be encouraged for effective disaster preparedness by the sharing of the experience, knowledge and technologies possessed by each company, and furthermore, that there be thorough dissemination to and sharing with affiliated companies by seminars conducted in the future based on this compilation of case studies.

Today, the twelve companies that are members of the Semiconductor Industry Association in Japan also agreed to mutual cooperation at the time of disaster. This agreement is that the companies will seek to provide continuity of product supply, contributing to customer and societal development, by clarifying a framework for collaboration and cooperation as the semiconductor industry in cases of damage suffered due to an earthquake or other disaster.

As an industry group, JEITA will contribute to customers and to society by building a framework for coordination at the time of an emergency response such as when a disaster occurs, while valuing healthy competition, leading to development of the industry. Announcements related to future initiatives will be provided on an as-needed basis.

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